

**LTM2883 32BGA 15mm X 11.25mm X 3.42mm (TABLE OF MATERIAL DECLARATION)**
*The LTM2883 is RoHS compliant per EU RoHS Directive 2003/95/EC.*

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1569	Barium Compounds	7727-43-7	0.00447	2.85
				Filler Substances (Silica Crystalline)/ Bismaleimide/Triazine	13776-74-4, 7631-86-9, non-disclosure	0.04649	29.63
				Copper Metal	7440-50-8	0.05652	36.02
				Copper Compounds	1328-53-6	0.00000	0.00
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00001	0.00
				Gold metal or alloy	7440-57-5	0.00036	0.23
				Nickel	7440-02-0	0.00232	1.48
				Zinc	7440-66-6	0.00006	0.04
				Bisphenol A Epoxy Resin	non-disclosure	0.00002	0.01
				Continuous Filament Fiber	14808-60-7	0.03653	23.28
				Acrylic Resin	non-disclosure	0.00852	5.43
				Epoxy Resin	non-disclosure	0.00020	0.13
				Chromium (III) Oxide	non-disclosure	0.00000	0.00
				Silica amorphous	7631-86-9	0.00005	0.04
				Talc;not containing fibers like asbestos	14807-96-9	0.00052	0.33
				Aromatic Carbonyl compounds	non-disclosure	0.00049	0.31
				Cyanoguanidine	461-58-5	0.00001	0.01
				Amine compounds	non-disclosure	0.00006	0.04
				Leveling agent and others	non-disclosure	0.00020	0.13
				Imidazole systemk curing agent	non-disclosure	0.00002	0.01
2	Solder Paste	Alloy	0.0004	Sn	7440-31-5	0.00042	95.00
				Sb	7440-36-0	0.00002	5.00
3	Epoxy		0.0010	Di-ester resin	non-disclosure	0.00010	0.10
				Functionalized ester	non-disclosure	0.00010	0.10
				Silver	7440-22-4	0.00080	0.80
4	Passive/Active Components		0.2470	Ni Oxide	1313-99-1	0.02116	8.57
				Cu Oxide	1317-38-0	0.00712	2.88
				Zn Oxide	1314-13-2	0.03222	13.04
				Fe Oxide	1309-37-1	0.11742	47.53
				iron Powder (Fe)	7439-89-6	0.00344	1.39
				Copper (Cu)	7440-50-8	0.05025	20.34
				Nickel (Ni)	7440-02-0	0.00144	0.58
				Tin (Sn)	7440-31-5	0.00361	1.46
				Ceramic (Ba Compounds)	12047-27-7	0.01035	4.19
5	Active IC's	Silicon	0.0041	Silicon	7440-21-3	0.00408	100.00
6	Wire	Gold	0.0028	Au	7440-57-5	0.00280	99.99
7	Solder Ball		0.0529	Sn	7440-31-5	0.05107	96.50
				Ag	7440-22-4	0.00159	3.00
				Cu	7440-50-8	0.00026	0.50
8	Encapsulation	Epoxy Resin	0.7029	Fused Silica	60676-86-0	0.54261	77.20
				Epoxy Resin	non-disclosure	0.06255	8.90
				Phenol Resin	non-disclosure	0.06255	8.90
				Crytalline Silica	14808-60-7	0.02109	3.00
				Carbon Black	1333-86-4	0.00351	0.50
				Metal Hydroxide	non-disclosure	0.01054	1.50
<b>Total Package Weight</b>			<b>1.1680</b>				

Note: Composition derived from MSDS and material C of C from Vendors; Component Weight based on assembly of generic parts